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(54) **EPOXY RESIN COMPOUND AND RADIANT HEAT CIRCUIT BOARD USING THE SAME**

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(58) **Field of Classification Search**

None

See application file for complete search history.

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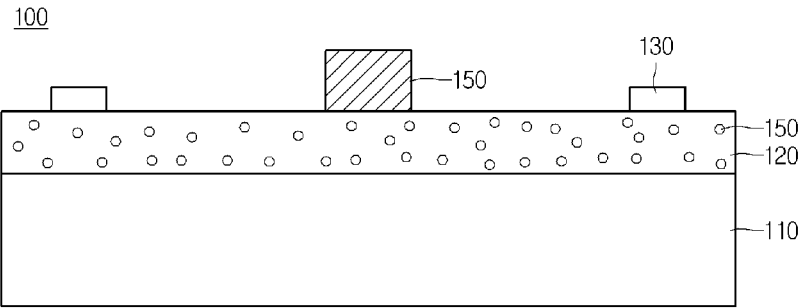
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(57) **ABSTRACT**

An epoxy resin composition having an epoxy resin, a curing agent, and inorganic filler as main components is provided. The epoxy resin includes an epoxy resin of Chemical Formula. Accordingly, the thermal conductivity of the epoxy resin composition can be increased because the epoxy resin has a mesogen structure that facilitates crystallizability. In addition, a high radiant heat board can be provided by using the above-mentioned epoxy resin as an insulating material for a printed circuit board.

**7 Claims, 1 Drawing Sheet**



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# EPOXY RESIN COMPOUND AND RADIANT HEAT CIRCUIT BOARD USING THE SAME

## CROSS-REFERENCE TO RELATED APPLICATIONS

This application is the U.S. national stage application of International Patent Application No. PCT/KR2012/003991, filed May 21, 2012, which claims priority to Korean Application No. 10-2011-0048109, filed May 20, 2011, the disclosures of each of which are incorporated herein by reference in their entirety.

## TECHNICAL FIELD

The present disclosure relates to an epoxy resin composition, and more particularly, to an epoxy resin for an insulating layer of a radiant heat circuit board.

## BACKGROUND ART

A circuit board includes an electric insulation board and a circuit pattern formed on the electric insulation board. Such a circuit board is used for mounting components such as electronic components thereon.

Such electronic components may include a heat-generating device such as a light emitting diode (LED) that generates a large amount of heat. Heat generated from such a heat-generating device increases the temperature of a circuit board and causes malfunction and reliability problems of the heat-generating device.

Accordingly, a radiant heat structure is important for dissipating heat from an electronic component to the outside of a circuit board, and the thermal conductivity of an insulating layer formed on the circuit board has a large influence on heat dissipation. The thermal conductivity of an insulating layer can be increased by filling an inorganic filler in the insulating layer at a high density, and an epoxy resin having a low viscosity is proposed as an inorganic filler.

Resins such as Bisphenol A type epoxy resin and bisphenol F type epoxy resin are generally used as low viscosity epoxy resins. Since such epoxy resins are difficult to handle because such epoxy resins are liquid at room temperature and are disadvantageous in terms of heat resistance, mechanical strength, and toughness.

## DISCLOSURE OF INVENTION

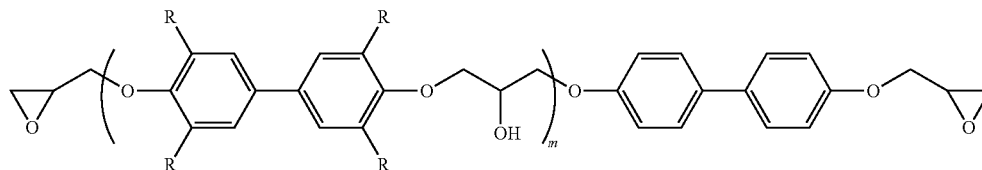
### Technical Problem

Embodiments provide an epoxy resin composition having a new composition ratio.

Embodiments provide a radiant heat circuit board with an improved thermal efficiency.

### Solution to Problem

Embodiments provide an epoxy resin composition including an epoxy resin, a curing agent, and inorganic filler as main components, wherein the epoxy resin includes an epoxy resin of the following Chemical Formula:



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(where m is an integer of 0 to 50.)

Embodiments also provide a radiant heat circuit board including a metal plate, an insulating layer on the metal plate, and a circuit pattern on the insulating layer, in which the insulating layer is formed by curing an epoxy resin composition including an epoxy resin, a curing agent, and inorganic filler as main components, and the epoxy resin includes the epoxy resin of the above Chemical Formula.

## Advantageous Effects of Invention

According to the present disclosure, thermal conductivity can be increased by using the epoxy resin having a mesogen structure that facilitates crystallizability. In addition, a high radiant heat board can be provided by using the epoxy resin as an insulating material for a printed circuit board.

The epoxy resin having a crystalline structure can be easily formed into a desired shape and be reliably used. In addition, the epoxy resin has high thermal conductivity, low absorptency, low thermal expansibility, and high heat resistance.

The details of one or more embodiments are set forth in the accompanying drawings and the description below. Other features will be apparent from the description and drawings, and from the claims.

## BRIEF DESCRIPTION OF DRAWINGS

FIG. 1 is a cross-sectional view illustrating a radiant heat circuit board according to an embodiment.

## MODE FOR THE INVENTION

Embodiments will now be described in detail with reference to the accompanying drawings in such a manner that the technical idea of the present disclosure may easily be carried out by a person of ordinary skill in the art. However, the scope and spirit of the present disclosure are not limited to the embodiments but can be realized in different forms.

In the specification, when it is described that one comprises (or includes or has) some elements, it should be understood that it may comprise (or include or have) only those elements, or it may comprise (or include or have) other elements as well as those elements if there is no specific limitation.

In the drawings, regions not relating to descriptions are omitted for clarity in description, and layers and regions are exaggerated for clarity. Throughout the specification, like reference numerals denote like elements.

It will be understood that when a layer, a film, a region, or a plate is referred to as being 'on' another layer, film, region, or plate, it can be directly on the other layer, film, region, or plate, or intervening layers, films, regions, or plates may also be present. However, if a layer, a film, a region, or a plate is referred to as being 'directly on' another layer, film, region, or plate, there is not intervening layer, film, region, or plate.

[Chemical Formula]

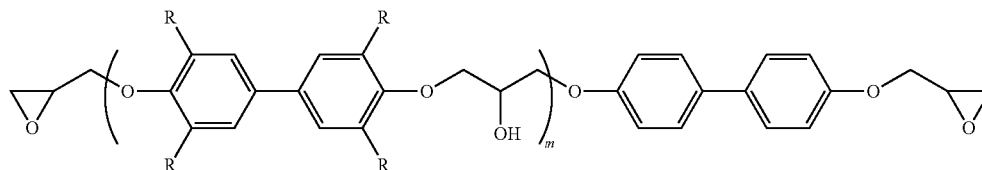
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The present disclosure provides an epoxy resin composition having an improved thermal conductivity owing to high crystalline characteristics.

The crystalline epoxy resin composition of the present disclosure includes an epoxy resin, a curing agent, and an inorganic filler as main components.

The epoxy resin may include at least 12 wt % of crystalline epoxy resin. For example, the epoxy resin may include at least 50 wt % of crystalline epoxy resin.

The crystalline epoxy resin is expressed by the following Chemical Formula.



where m is an integer of 0 to 50.

In Chemical Formula, R may be hydrogen or an alkyl group.

If the content of the crystalline epoxy resin is less than the above-mentioned value, effects such as an increase in thermal conductivity are reduced because the epoxy resin is not crystallized when hardened.

The epoxy resin further includes a general amorphous epoxy resin in which a molecule has at least two epoxy groups as well as the crystalline epoxy resin which is an essential component.

Examples of the amorphous epoxy include: bisphenol A; 3,3',5,5'-tetramethyl-4,4'-dihydroxydiphenylmethane; 4,4'-dihydroxydiphenylsulfone; 4,4'-dihydroxydiphenylsulfide; 4,4'-dihydroxydiphenylketone; fluorenbisphenol; 4,4'-biphenol-1,3,3',5,5'-tetramethyl-4,4'-dihydroxybiphenyl; 2,2'-biphenol; resorcin; catechol; t-butylcatechol; hydroquinone; t-butylhydroquinone; 1,2-dihydroxynaphthalene; 1,3-dihydroxynaphthalene; 1,4-dihydroxynaphthalene; 1,5-dihydroxynaphthalene; 1,6-dihydroxynaphthalene; 1,7-dihydroxynaphthalene; 1,8-dihydroxynaphthalene; 2,3-dihydroxynaphthalene; 2,4-dihydroxynaphthalene; 2,5-dihydroxynaphthalene; 2,6-dihydroxynaphthalene; 2,7-dihydroxynaphthalene; 2,8-dihydroxynaphthalene; allylated compounds or polyallylated compounds of the dihydroxynaphthalene; divalent phenols such as allylated bisphenol A, allylated bisphenol F, allylated phenol novolac; phenols having a valence of three or more such as phenol novolac, bisphenol A novolac, o-cresol novolac, m-cresol novolac, p-cresol novolac, Xylenole novolac, poly-p-hydroxystyrene, tris-(4-hydroxyphenyl)methane, 1,1,2,2-tetrakis(4-hydroxyphenyl)ethane, fluoroglycinol, pyrogallol, t-butylpyrogallol, allylated pyrogallol, polyallylated pyrogallol, 1,2,4-benzenetriol, 2,3,4-trihydroxybenzophenone, phenolalkyl resin, naphthol alkyl resin, dicyclopentadiene-based resin; and glycidyl etherficated compounds derived from halogenated bisphenols such as tetrabromobisphenol A. For example, the epoxy resin may include a combination of two or more of the listed amorphous epoxy resins.

The curing agent used for the epoxy resin composition of the present disclosure may be any of generally known epoxy resin curing agent. For example, the curing agent may be a phenol-based curing agent.

The phenol-based curing agent includes a phenol resin in addition to a phenol compound.

Examples of the phenol-based curing agent includes bisphenol A, bisphenol F, 4,4'-dihydroxydiphenylmethane,

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4,4'-dihydroxyphenylether, 1,4-bis(4-hydroxyphenoxy)benzene, 1,3-bis(4-hydroxyphenoxy)benzene, 4,4'-dihydroxydiphenylsulfide, 4,4'-dihydroxydiphenylketone, 4,4'-dihydroxydiphenylsulfone, 4,4'-dihydroxybiphenyl, 2,2'-dihydroxybiphenyl, 10-(2,5-dihydroxyphenyl)-10H-9-oxa-10-phosphaphenanthrene-10-oxide, phenol novolac, bisphenol A novolac, o-cresol novolac, m-cresol novolac, p-cresol novolac, Xylenole novolac, poly-p-hydroxystyrene, hydroquinone, resorsin, catechol, t-butylcatechol, t-butyl hydroquinone, fluoroglycinol, pyrogallol, t-butylpyrogallol, allylated pyrogallol, polyallylated pyrogallol, 1,2,4-benzen-

[Chemical Formula]

etriol, 2,3,4-trihydroxybenzophenone, 1,2-dihydroxynaphthalene, 1,3-dihydroxynaphthalene, 1,4-dihydroxynaphthalene, 1,5-dihydroxynaphthalene, 1,6-dihydroxynaphthalene, 1,7-dihydroxynaphthalene, 1,8-dihydroxynaphthalene, 2,3-dihydroxynaphthalene, 2,4-dihydroxynaphthalene, 2,5-dihydroxynaphthalene, 2,6-dihydroxynaphthalene, 2,7-dihydroxynaphthalene, 2,8-dihydroxynaphthalene, allylated compounds or polyallylated compounds of the dihydroxynaphthalene, allylated bisphenol A, allylated bisphenol F, allylated phenol novolac, and allylated pyrogallol.

At least two curing agents may be mixed and then used as the curing agent.

Meanwhile, a generally known curing agent may be used in addition to the phenol-based curing agent. Examples of generally known curing agent include an amine-based curing agent, an acid anhydride-based curing agent, a phenol-based curing agent, a polymercaptan-based curing agent, a polyaminoamide-based curing agent, an isocyanate-based curing agent, and a block isocyanate-based curing agent. The mixing ratio of the above curing agents may be properly selected according to the type of curing agent to be mixed or physical properties of a thermal conductive epoxy resin product.

Examples of the amine-based curing agent include aliphatic amines, polyetherpolyamines, cycloaliphatic amines, and aromatic amines. Examples of the aliphatic amines include ethylene diamine, 1,3-diaminopropane, 1,4-diaminopropane, hexamethylenediamine, 2,5-dimethylhexamethylenediamine, trimethylhexamethylenediamine, diethylenetriamine, aminobispropylamine, bis(hexamethylene) triamine, triethylenetetramine, tetraethylenepentamine, pentaethylenhexamine, N-hydroxyethylethylenediamine, and tetra(hydroxyethyl)ethylenediamine. Examples of the polyetherpolyamines include triethyleneglycoldiamine, tetraethyleneglycoldiamine, diethyleneglycolbis(propylamine), polyoxypropylenediamine, and polyoxypropylenetriamines. Examples of the cycloaliphatic amines include isophorone diamine, metacendiamine, N-aminoethylpiperazine, bis(4-amino-3-methylcyclohexyl)methane, bis(aminomethyl)cyclohexane, 3,9-bis(3-aminopropyl)2,4,8,10-tetraoxaspiro(5,5)undecane, and norbornene diamine. Examples of the aromatic amines include tetrachloro-p-xylylenediamine, m-xylylenediamine, p-xylylenediamine, m-phenylenediamine, o-phenylenediamine, pphenylenediamine, 2,4-diaminoanisole, 2,4-toluenediamine, 2,4-diaminodiphenylmethane, 4,4'-diaminodiphenylmethane, 4,4'-diamino-1,2-diphenylethane, 2,4-diaminodiphenylsulfone, 4,4'-diaminodiphenylsulfone, m-aminophenol, m-amin-

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obenzylamine, benzyltrimethylamine, 2-dimethylaminomethylphenol, triethanolphenol, methylbenzylamine,  $\alpha$ -(*m*-aminophenyl)ethylamine,  $\alpha$ -(*p*-aminophenyl)ethylamine, diaminodiethylmethyldiphenylmethane, and  $\alpha,\alpha'$ -bis(4-aminophenyl)-*p*-diisopropylbenzene.

Examples of the acid anhydride curing agent include dodecenyl succinic anhydride, polyadipic acid anhydride, polyazellainic acid anhydride, polysebacic acid anhydride, poly(ethyloctadecanoic acid)anhydride, poly(phenylhexadecanoic acid)anhydride, methyltetrahydro phthalic anhydride, methylhexahydro phthalic anhydride, hexahydro phthalic anhydride, anhydrous methyl hymic acid, tetrahydro phthalic anhydride, trialkyltetrahydro phthalic anhydride, methylcyclohexenedicarboxylic acid anhydride, methylcyclohexenetetracarboxylic acid anhydride, phthalic anhydride, anhydrous trimellitic acid, anhydrous pyromellitic acid, benzophenone tetracarboxylic acid anhydride, ethylene glycol bistrimellitate, hetic anhydride, nadic anhydride, anhydrous methyl nadic acid, 5-(2,5-dioxotetrahydro-3-furanyl)-3-methyl-3-cyclohexane-1,2-dicarboxylic acid anhydride, 3,4-dicarboxy-1,2,3,4-tetrahydro-1-naphthalene succinic acid dianhydride, and 1-methyl-dicarboxy-1,2,3,4-tetrahydro-1-naphthalene succinic acid dianhydride.

The epoxy resin composition includes 40 wt % to 97 wt % of the inorganic filler.

When the content of the inorganic filler is lower than the above range, it may be difficult to attain effects of the present disclosure such as high thermal conductivity, low thermal expansibility, and high thermal resistance. The more the content of inorganic filler is included, the above-mentioned effects can be attained but are not improved in proportion to the volume fraction of the inorganic filler. That is, the above-mentioned effects are significantly improved from a specific content of the inorganic filler. The above-described mentioned effects are obtained by controlled high order structure in a polymer state. It seems that a specific content of the inorganic filler is necessary because the higher order structure is mainly achieved on the surface of the inorganic filler. Meanwhile, when the content of the inorganic filler is greater than the above range, the viscosity of the epoxy resin composition may increase to make it difficult to form the epoxy resin composition in a desired shape.

The inorganic filler may have a globular shape. The shape of the inorganic filler is not limited as long as the inorganic filler has a globular shape. For example, the inorganic filler may have an elliptical sectional shape. However, as the shape of the inorganic filler is close to a perfect globular shape, the fluidity of the epoxy resin composition improves.

The inorganic filler may be alumina, aluminum nitride, silicon nitride, boron nitride, or crystalline silica, and the like. In addition, two or more different inorganic fillers may be used in combination as the inorganic filler.

The average particle diameter of the inorganic filler may be less than 30  $\mu\text{m}$ . When the average particle diameter is above the above range, the fluidity and strength of the epoxy resin composition are decreased.

The epoxy resin composition of the present disclosure may be mixed with a known curing accelerator. Examples of the curing accelerator include amines, imidazoles, organic phosphines, and Lewis acids. Specifically, examples of the curing accelerator may include: tertiary amines such as 1,8-diazabicyclo(5,4,0)undecene-7, triethylenediamine, benzyltrimethylamine, triethanolamine, dimethylaminoethanol, and tris(dimethylaminomethyl)phenol; imidazoles such as 2-methylimidazole, 2-phenylimidazole, 2-phenyl-4-methylimidazole, and 2-heptadecylimidazole; organic phosphines such as tributylphosphine, methyldiphenylphosphine, triphenylphosphine, diphenylphosphine, and phenylphosphine; and tetra substituted phosphonium.tetra substituted borate such as tetraphenylphosphonium.tetraphenylborate, tetraphenylphosphonium.ethyltriphenylborate, and tetrabutylphosphonium.tetrabutylborate; and tetra-

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phenylboron salts such as 2-ethyl-4-methylimidazole.tetraphenylborate, and N-methylmorpholin.tetraphenylborate.

General wax may be used as a release agent for wax may be used as a release agent for the epoxy resin composition of the present disclosure. Examples of the wax include stearic acid, montanic acid, montanic acid ester, and phosphoric acid ester.

For the epoxy resin composition of the present disclosure, a coupling agent that is generally used for an epoxy resin composition may be used so as to improve the adhesion strength between the inorganic filler and the resin component. Examples of the coupling agent include an epoxy silane.

When the epoxy resin composition of the present disclosure includes the epoxy resin, the curing agent, and the inorganic filler as main components, the epoxy resin composition includes 3 wt % to 60 wt % of the epoxy resin, 40 wt % to 97 wt % of the inorganic filler, and 0.5 wt % to 5 wt % of the curing agent. The epoxy resin, the curing agent, and other components are dissolved in a solvent such as acetone, MEK, MIBK, IPA, butanol, or toluene and are agitated while applying heat. Then, the inorganic filler is added to the solution is uniformly mixed using a device such as a mixer. Thereafter, the coupling agent is added to the mixture and the mixture is kneaded using a device such as a heating roll and a kneader. The mixing order of the above components is not limited.

At this time, the solvent is used in 10 wt % to 20 wt % based on the total weight of the epoxy resin composition.

The epoxy resin composition of the present disclosure may be applied to a radiant heat circuit board **100** as shown in FIG. 1.

Referring to FIG. 1, the radiant heat circuit board **100** of the present disclosure includes a metal plate **110**, an insulating layer **120** on the metal plate **110**, circuit patterns **130** on the insulating layer **120**.

The metal plate **110** may be formed of one of alloys including copper, aluminum, nickel, gold, platinum, and the like that have good thermal conductivity.

The metal plate **110** may include a metal projection (now shown) that constitutes a mounting pad on which a heat-generating device **150** is mounted.

The metal projection may extend vertically from the metal plate **110**. The heat-generating device **150** is mounted on a portion of the top side of the metal projection, and the portion of the top side of the metal projection has a predetermined width so that solder balls can be placed.

The insulating layer **120** is disposed on the metal plate **110**.

The insulating layer **120** may include a plurality of insulating layers. The insulating layer **120** is disposed between the metal plate **110** and the circuit patterns **130**.

The insulating layer **120** may be formed by curing the above-described crystalline epoxy resin composition. An inorganic filler **125** is evenly dispersed in the insulating layer **120**.

The circuit patterns **130** are disposed on the insulating layer **120**.

Since the insulating layer **120** is formed of the above-described crystalline epoxy resin composition, the thermal conductivity of the insulating layer **120** is increased so that heat generated from the heat-generating device **150** can be transferred to the metal plate **110** through the insulating layer **120**.

## EXAMPLES

Hereinafter, the scope and spirit of the present disclosure will be explained in more detail with reference to Examples.

### Example 1

All of 10.7 wt % of Bisphenol-A, 3.2 wt % of o-cresol-novolac, 2.1 wt % of crystalline epoxy resin of Chemical

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Formula 1, 1.8 wt % of Tetraphenylphosphonium tetraphenylborate (TPP-K) curing agent and epoxy resin of 6.4 wt % of multiaromatic resin, 0.3 wt % of imidazole-based curing accelerator, and 0.5 wt % of BYK-W980 additive were mixed; stirred at 40° C. for 10 minutes; then 74.9 wt % of alumina inorganic filler was added; and then stirred at room temperature for 20 to 30 minutes to obtain a crystalline epoxy resin composition of Example 1.

The thermal conductivity of the epoxy resin composition was measured by an unsteady hot wire method using LFA447 Type thermal conductivity meter available from NETZSCH Company.

Melting heat of the epoxy resin composition was measured at a temperature increasing rate of 10° C./minute by using a differential scanning calorimeter (DSC Q100 available from TA Company).

The glass transition temperature of the epoxy resin composition was measured at a temperature increasing rate of 10° C./minute by using a DSC Q100 Thermo-mechanical measuring device available from TA Company.

#### Example 2

All of 3.1 wt % of o-cresol-novolac, 3.1 wt % of crystalline epoxy resin of Chemical Formula 1, 2.3 wt % of imidazole-based curing agent and epoxy resin of 7.3 wt % of multiaromatic resin, 0.2 wt % of imidazole-based curing accelerator, and 0.7 wt % of BYK-W980 additive were mixed; stirred at 40° C. for 10 minutes; then 83.2 wt % of alumina inorganic filler was added; and then stirred at room temperature for 20 to 30 minutes to obtain a crystalline epoxy resin composition of Example 2.

#### Example 3

All of 1.9 wt % of Bisphenol-A, 7.5 wt % of crystalline epoxy resin of Chemical Formula 1, 0.8 wt % of imidazole-based curing agent and epoxy resin of 4.7 wt % of multiaromatic resin, 0.1 wt % of imidazole-based curing accelerator, and 0.7 wt % of BYK-W980 additive were mixed; stirred at 40° C. for 10 minutes; then 84.3 wt % of alumina inorganic filler was added; and then stirred at room temperature for 20 to 30 minutes to obtain a crystalline epoxy resin composition of Example 3.

#### Example 4

All of 1.8 wt % of Bisphenol-A, 10.6 wt % of crystalline epoxy resin of Chemical Formula 1, 0.8 wt % of imidazole-based curing agent and epoxy resin of 4.4 wt % of multiaromatic resin, 0.1 wt % of imidazole-based curing accelerator, and 0.7 wt % of BYK-W980 additive were mixed; stirred at 40° C. for 10 minutes; then 81.6 wt % of alumina inorganic filler was added; and then stirred at room temperature for 20 to 30 minutes to obtain a crystalline epoxy resin composition of Example 4.

#### Example 5

All of 0.9 wt % of Bisphenol-A, 6.4 wt % of crystalline epoxy resin of Chemical Formula 1, 0.8 wt % of imidazole-based curing agent and epoxy resin of 4.6 wt % of multiaromatic resin, 0.1 wt % of imidazole-based curing accelerator, and 0.7 wt % of BYK-W980 additive were mixed; stirred at 40° C. for 10 minutes; then 86.5 wt % of alumina inorganic filler was added; and then stirred at room temperature for 20 to 30 minutes to obtain a crystalline epoxy resin composition of Example 5.

#### Comparative Example 1

All of 17.1 wt % of Bisphenol-A, 2.7 wt % of phenol novolac, 2.7 wt % of o-cresol-novolac, 2.1 wt % of phenol

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based curing agent and epoxy resin of 5.5 wt % of multiaromatic resin, 0.7 wt % of imidazole-based curing accelerator, and 0.7 wt % of BYK-W980 additive were mixed; stirred at 40° C. for 10 minutes; then 68.5 wt % of alumina inorganic filler was added; and then stirred at room temperature for 20 to 30 minutes to obtain an epoxy resin composition of Comparative Example 1.

#### Comparative Example 2

All of 11.8 wt % of Bisphenol-A, 3.5 wt % of phenol novolac, 3.5 wt % of o-cresol-novolac, 2.5 wt % of phenol-based curing agent and epoxy resin of 7.1 wt % of multiaromatic resin, 0.5 wt % of imidazole-based curing accelerator, and 0.6 wt % of BYK-W980 additive were mixed; stirred at 40° C. for 10 minutes; then 70.6 wt % of alumina inorganic filler was added; and then stirred at room temperature for 20 to 30 minutes to obtain an epoxy resin composition of Comparative Example 2.

#### Comparative Example 3

All of 10.7 wt % of Bisphenol-A, 1.8 wt % of phenol novolac, 1.8 wt % of o-cresol-novolac, 1.3 wt % of phenol-based curing agent and epoxy resin of 3.6 wt % of multiaromatic resin, 0.4 wt % of imidazole-based curing accelerator, and 0.4 wt % of BYK-W980 additive were mixed; stirred at 40° C. for 10 minutes; then 80.0 wt % of alumina inorganic filler was added; and then stirred at room temperature for 20 to 30 minutes to obtain an epoxy resin composition of Comparative Example 3.

#### Experimental Example

##### Measurement of Thermal Conductivity

Thermal conductivities of each Example and Comparative Example were measured by an unsteady hot wire method using LFA447 Type thermal conductivity meter available from NETZSCH Company, and the measured results are shown in Table 1.

Referring to Table 1, in Example 4 and Comparative Example 3 where the same amount of inorganic filler was used, the thermal conductivity of the crystalline epoxy resin composition of Example 4 including a crystalline epoxy resin is higher than the thermal conductivity of the epoxy resin composition of Comparative Example 3.

##### Measurement of Heat of Melting

Melting heat was measured at a temperature increasing rate of 10° C./minute using a differential scanning calorimeter (DSC Q100 available from TA Company), and the measured results are shown in Table 1. The melting heat is similar in each Example and Comparative Example.

##### Glass Transition Temperature

Glass transition temperatures were measured at a temperature increasing rate of 10° C./minute by using a DSC Q100 Thermo-mechanical measuring device available from TA Company, and the measured results are shown in Table 1. The glass transition temperatures are at least 100° C. That is, other properties are not deteriorated although a crystalline epoxy resin is added. Although embodiments have been described with reference to a number of illustrative embodiments thereof, it should be understood that numerous other modifications and embodiments can be devised by those skilled in the art that will fall within the spirit and scope of the principles of this disclosure. More particularly, various variations and modifications are possible in the component parts and/or arrangements of the subject combination arrangement within the scope of the disclosure, the drawings and the appended claims. In addition to variations and

modifications in the component parts and/or arrangements, alternative uses will also be apparent to those skilled in the art.

TABLE 1

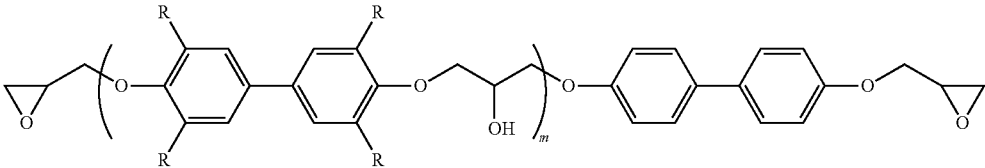
Experiment No.	Thermal Conductivity (W/m · K)	Glass Transition Temperature Tg (° C.)	Heat of Melting (J/g)
Example 1	1.73	109	286
Example 2	1.89	126	240
Example 3	3.93	119	312
Example 4	5.52	124	324
Example 5	2.98	122	297
Comparative Example 1	0.63	104	243
Comparative Example 2	1.52	115	297

TABLE 1-continued

Experiment No.	Thermal Conductivity (W/m · K)	Glass Transition Temperature Tg (° C.)	Heat of Melting (J/g)
Comparative Example 3	2.865	124.78	249.2

The invention claimed is:  
1. A radiant heat circuit board comprising:  
a metal plate;  
an insulating layer on the metal plate; and  
a circuit pattern on the insulating layer,  
wherein the insulating layer is formed by curing an epoxy resin composition comprising an epoxy resin, a curing agent, and an inorganic filler,  
wherein the epoxy resin comprises crystalline epoxy resin and non-crystalline epoxy resin,  
wherein the crystalline epoxy resin is represented by the following Chemical Formula:

[Chemical Formula]



where m is an integer from 0 to 50, and R is hydrogen or alkyl group,  
and wherein the crystalline epoxy resin of the Chemical Formula is included at 53 wt % to 63 wt % with respect to a total weight of the epoxy resin.  
2. The radiant heat circuit board according to claim 1, wherein the epoxy resin composition comprises 40 wt % to 97 wt % of the inorganic filler.  
3. The radiant heat circuit board according to claim 1, wherein the inorganic filler is at least one of alumina, boron nitride, aluminum nitride, crystalline silica, and silicon nitride.  
4. The radiant heat circuit board according to claim 1, wherein if the epoxy resin composition comprises at least 90 wt % of the inorganic filler, the epoxy resin composition has a thermal conductivity of at least 3 W/m·K.  
5. The radiant heat circuit board according to claim 1, wherein the epoxy resin composition comprises 3 wt % to 60 wt % of the epoxy resin.  
6. The radiant heat circuit board according to claim 1, wherein the epoxy resin composition comprises 0.5 wt % to 5 wt % of the curing agent.  
7. The radiant heat circuit board according to claim 1, wherein the epoxy resin composition further comprises a curing accelerator and a coupling agent.

\* \* \* \* \*